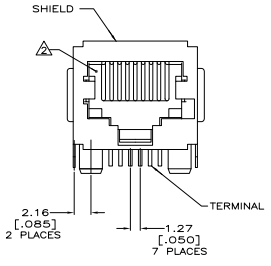
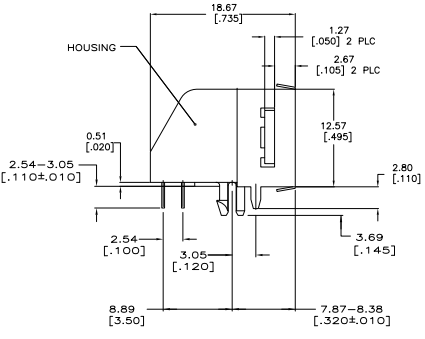


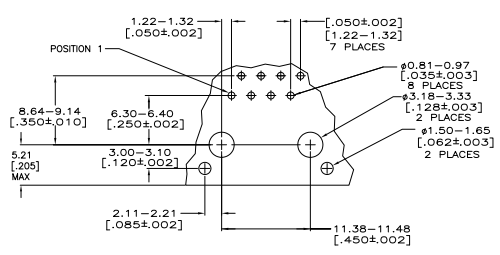
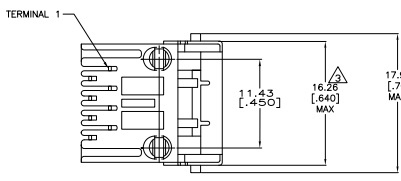
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REV	DATE	DESCRIPTION	BY	CHK
AA	00			
C		E20-08-002714	DEFREDDO	LAM PR

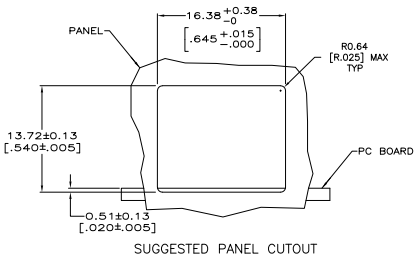


1. MATERIAL:
 HOUSING—PBT POLYESTER BLACK.
 TERMINAL— 0.36 [.014] THICK PHOS—BRONZE PLATE WITH 1.27μm [.000050] MIN THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.9μm [.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27μm [.000050] MIN THICK NICKEL UNDERPLATE.
 SHIELD— 0.25 [.010] THICK COPPER ALLOY, PLATE WITH 3.0μm [.000120] MIN THICK REFLOWED TIN

△ CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68, SUBPART F.
 △ DIMENSION MEASURED ALONG FRONT EDGE OF MATING SURFACE



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
 COMPONENT SIDE



SUGGESTED PANEL CUTOUT

5558382-1
 PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		APPROVED BY	DATE	REVISED BY	DATE	REVISED BY	DATE
DRAWN BY		DATE	REVISED BY	DATE	REVISED BY	DATE	REVISED BY
CHECKED BY		DATE	REVISED BY	DATE	REVISED BY	DATE	REVISED BY
SEE NOTE 1		SEE NOTE 1	SEE NOTE 1	SEE NOTE 1	SEE NOTE 1	SEE NOTE 1	SEE NOTE 1
CUSTOMER DRAWING		DATE	REVISED BY	DATE	REVISED BY	DATE	REVISED BY

5558382-1
 TTI Electronics Corporation
 Harrisburg, Pa 17105-3008
 MODULAR JACK ASSEMBLY, POSITION,
 SHIELDED, KEYED, LOW PROFILE, RIGHT ANGLE,
 WITH PANEL GROUNDS AND PANEL STOPS
 108-1163
 114-2048
 A100779
 G=5558382
 SHEET 4 OF 1